

ABSTRACT

Memory systems and methods are described. In one embodiment, a circuit board has front and back surfaces. At least one memory device having a plurality of pins is mounted on the front surface of the circuit board. At least one other memory device having a plurality of pins is mounted on the back surface of the circuit board. The memory devices are mounted on the circuit board such that at least some pins from the one memory device align with at least some pins of the other memory device to provide aligned pin pairs. A via is disposed in the circuit board and extends between and connects individual pins of an aligned pin pair.